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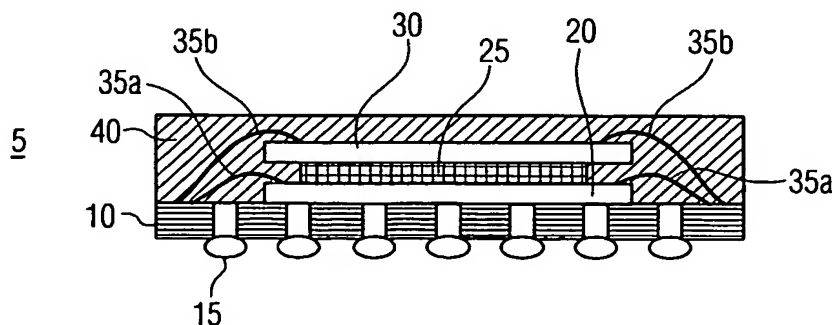
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— as to the applicant's entitlement to claim the priority of the  
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[Continued on next page]

(54) Title: ELECTRICAL SHIELDING IN STACKED DIES BY USING CONDUCTIVE DIE ATTACH ADHESIVE



(57) Abstract: In example  
embodiment, there is an integrated  
circuit (IC) device (5) assembled  
in a package (5) having a plurality  
of die including a first device  
(20) and at least one additional  
device (30). The IC comprises  
a substrate (10). A first device  
die (20), having bonding pads  
including ground connections, is  
die attached to the substrate (10).  
An additional device die (30),  
having bonding pads including  
ground connections is disposed  
on top of the first device die (20).

The additional device die is die attached to the first device die. The ground connections of the first device die are connected to the ground connections of the additional device die in order to minimize the electrical interference between the device dies. An additional feature of the embodiment is, ground connections of the first device are connected to the ground connections of the additional device with a conductive adhesive (25).



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